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Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	359200
Number of Logic Elements/Cells	952000
Total RAM Bits	53248000
Number of I/O	600
Number of Gates	-
Voltage - Supply	0.87V ~ 0.93V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	1760-BBGA, FCBGA
Supplier Device Package	1760-HBGA (45x45)
Purchase URL	https://www.e-xfl.com/product-detail/intel/5sgxebbr2h43i2n

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Table 11. OCT Calibration Accuracy Specifications for Stratix V Devices (1) (Part 2 of 2)

				Calibratio	n Accuracy		
Symbol	Description	Conditions	C1	C2,I2	C3,I3, I3YY	C4,I4	Unit
50-Ω R _S	Internal series termination with calibration (50- Ω setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%
$34\text{-}\Omega$ and $40\text{-}\Omega$ R_S	Internal series termination with calibration (34- Ω and 40- Ω setting)	V _{CCIO} = 1.5, 1.35, 1.25, 1.2 V	±15	±15	±15	±15	%
48 - Ω , 60 - Ω , 80 - Ω , and 240 - Ω R _S	Internal series termination with calibration (48- Ω , 60- Ω , 80- Ω , and 240- Ω setting)	V _{CCIO} = 1.2 V	±15	±15	±15	±15	%
50-Ω R _T	Internal parallel termination with calibration (50-Ω setting)	V _{CCIO} = 2.5, 1.8, 1.5, 1.2 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
$\begin{array}{c} 20\text{-}\Omega,30\text{-}\Omega,\\ 40\text{-}\Omega,60\text{-}\Omega,\\ \text{and}\\ 120\text{-}\OmegaR_T \end{array}$	Internal parallel termination with calibration (20- Ω , 30- Ω , 40- Ω , 60- Ω , and 120- Ω setting)	V _{CCIO} = 1.5, 1.35, 1.25 V	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
60- Ω and 120- Ω R _T	Internal parallel termination with calibration (60- Ω and 120- Ω setting)	V _{CCIO} = 1.2	-10 to +40	-10 to +40	-10 to +40	-10 to +40	%
$\begin{array}{c} \textbf{25-}\Omega \\ \textbf{R}_{S_left_shift} \end{array}$	Internal left shift series termination with calibration (25- Ω R _{S_left_shift} setting)	V _{CCIO} = 3.0, 2.5, 1.8, 1.5, 1.2 V	±15	±15	±15	±15	%

Note to Table 11:

Table 12 lists the Stratix V OCT without calibration resistance tolerance to PVT changes.

Table 12. OCT Without Calibration Resistance Tolerance Specifications for Stratix V Devices (Part 1 of 2)

			Re	sistance	Tolerance		
Symbol	Description	Conditions	C1	C2,I2	C3, I3, I3YY	C4, I4	Unit
25-Ω R, 50-Ω R _S	Internal series termination without calibration (25- Ω setting)	V _{CCIO} = 3.0 and 2.5 V	±30	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25- Ω setting)	V _{CCIO} = 1.8 and 1.5 V	±30	±30	±40	±40	%
25-Ω R _S	Internal series termination without calibration (25- Ω setting)	V _{CCIO} = 1.2 V	±35	±35	±50	±50	%

⁽¹⁾ OCT calibration accuracy is valid at the time of calibration only.

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Internal Weak Pull-Up Resistor

Table 16 lists the weak pull-up resistor values for Stratix V devices.

Table 16. Internal Weak Pull-Up Resistor for Stratix V Devices (1), (2)

Symbol	Description	V _{CC10} Conditions (V) ⁽³⁾	Value ⁽⁴⁾	Unit
		3.0 ±5%	25	kΩ
		2.5 ±5%	25	kΩ
	Value of the I/O pin pull-up resistor before	1.8 ±5%	25	kΩ
R _{PU}	and during configuration, as well as user mode if you enable the programmable	1.5 ±5%	25	kΩ
	pull-up resistor option.	1.35 ±5%	25	kΩ
		1.25 ±5%	25	kΩ
		1.2 ±5%	25	kΩ

Notes to Table 16:

- (1) All I/O pins have an option to enable the weak pull-up resistor except the configuration, test, and JTAG pins.
- (2) The internal weak pull-down feature is only available for the JTAG TCK pin. The typical value for this internal weak pull-down resistor is approximately 25 k Ω .
- (3) The pin pull-up resistance values may be lower if an external source drives the pin higher than V_{CCIO} .
- (4) These specifications are valid with a ±10% tolerance to cover changes over PVT.

I/O Standard Specifications

Table 17 through Table 22 list the input voltage (V_{IH} and V_{IL}), output voltage (V_{OH} and V_{OL}), and current drive characteristics (I_{OH} and I_{OL}) for various I/O standards supported by Stratix V devices. These tables also show the Stratix V device family I/O standard specifications. The V_{OL} and V_{OH} values are valid at the corresponding I_{OH} and I_{OL} , respectively.

For an explanation of the terms used in Table 17 through Table 22, refer to "Glossary" on page 65. For tolerance calculations across all SSTL and HSTL I/O standards, refer to Altera knowledge base solution rd07262012_486.

Table 17. Single-Ended I/O Standards for Stratix V Devices

1/0		V _{CCIO} (V)		VII	_(V)	V _{IH}	(V)	V _{OL} (V)	V _{OH} (V)	I _{OL}	I _{OH}
Standard	Min	Тур	Max	Min	Max	Min	Max	Max	Min	(mĀ)	(mA)
LVTTL	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.4	2.4	2	-2
LVCMOS	2.85	3	3.15	-0.3	0.8	1.7	3.6	0.2	V _{CCIO} - 0.2	0.1	-0.1
2.5 V	2.375	2.5	2.625	-0.3	0.7	1.7	3.6	0.4	2	1	-1
1.8 V	1.71	1.8	1.89	-0.3	0.35 * V _{CCIO}	0.65 * V _{CCIO}	V _{CCIO} + 0.3	0.45	V _{CCIO} – 0.45	2	-2
1.5 V	1.425	1.5	1.575	-0.3	0.35 * V _{CCIO}	0.65 * V _{CCIO}	V _{CCIO} + 0.3	0.25 * V _{CCIO}	0.75 * V _{CCIO}	2	-2
1.2 V	1.14	1.2	1.26	-0.3	0.35 * V _{CCIO}	0.65 * V _{CCIO}	V _{CCIO} + 0.3	0.25 * V _{CCIO}	0.75 * V _{CCIO}	2	-2

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 6 of 7)

Symbol/	Conditions	Trai	nsceive Grade	r Speed e 1	Trar	sceive Grade	r Speed 2	Tran	sceive Grade	er Speed e 3	Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
Inter-transceiver block transmitter channel-to- channel skew	xN PMA bonded mode	ı	ı	500	_	ı	500	_	_	500	ps
CMU PLL											
Supported Data Range	_	600	_	12500	600	_	12500	600	_	8500/ 10312.5 (24)	Mbps
t _{pll_powerdown} (15)	_	1	_	_	1	_	_	1	_	_	μs
t _{pll_lock} (16)	_	_	_	10	_	_	10	_	_	10	μs
ATX PLL											
	VCO post-divider L=2	8000	_	14100	8000	_	12500	8000	_	8500/ 10312.5 (24)	Mbps
Currented Date	L=4	4000	_	7050	4000	_	6600	4000		6600	Mbps
Supported Data Rate Range	L=8	2000	_	3525	2000	_	3300	2000	_	3300	Mbps
Ç	L=8, Local/Central Clock Divider =2	1000	_	1762.5	1000	_	1762.5	1000	_	1762.5	Mbps
t _{pll_powerdown} (15)	_	1	_	_	1	_	_	1	_	_	μs
t _{pll_lock} (16)	_			10	_		10	_		10	μs
fPLL											
Supported Data Range	_	600	_	3250/ 3125 ⁽²⁵⁾	600	_	3250/ 3125 ⁽²⁵⁾	600	_	3250/ 3125 ⁽²⁵⁾	Mbps
t _{pll_powerdown} (15)	_	1	_	_	1	_	_	1	_		μs

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Table 23. Transceiver Specifications for Stratix V GX and GS Devices (1) (Part 7 of 7)

Symbol/ Description Conditions		Trai	Transceiver Speed Grade 1		Transceiver Speed Grade 2			Transceiver Speed Grade 3			Unit
Description		Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	
t _{pll_lock} (16)	_	_	_	10	_	_	10	_	_	10	μs

Notes to Table 23:

- (1) Speed grades shown in Table 23 refer to the PMA Speed Grade in the device ordering code. The maximum data rate could be restricted by the Core/PCS speed grade. Contact your Altera Sales Representative for the maximum data rate specifications in each speed grade combination offered. For more information about device ordering codes, refer to the *Stratix V Device Overview*.
- (2) The reference clock common mode voltage is equal to the V_{CCR_GXB} power supply level.
- (3) This supply must be connected to 1.0 V if the transceiver is configured at a data rate > 6.5 Gbps, and to 1.05 V if configured at a data rate > 10.3 Gbps when DFE is used. For data rates up to 6.5 Gbps, you can connect this supply to 0.85 V.
- (4) This supply follows VCCR_GXB.
- (5) The device cannot tolerate prolonged operation at this absolute maximum.
- (6) The differential eye opening specification at the receiver input pins assumes that **Receiver Equalization** is disabled. If you enable **Receiver Equalization**, the receiver circuitry can tolerate a lower minimum eye opening, depending on the equalization level.
- (7) The Quartus II software automatically selects the appropriate slew rate depending on the configured data rate or functional mode.
- (8) The input reference clock frequency options depend on the data rate and the device speed grade.
- (9) The line data rate may be limited by PCS-FPGA interface speed grade.
- (10) Refer to Figure 1 for the GX channel AC gain curves. The total effective AC gain is the AC gain minus the DC gain.
- (11) t_{LTR} is the time required for the receive CDR to lock to the input reference clock frequency after coming out of reset.
- (12) t_{I TD} is time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high.
- (13) t_{LTD_manual} is the time required for the receiver CDR to start recovering valid data after the rx_is_lockedtodata signal goes high when the CDR is functioning in the manual mode.
- (14) t_{LTR_LTD_manual} is the time the receiver CDR must be kept in lock to reference (LTR) mode after the rx_is_lockedtoref signal goes high when the CDR is functioning in the manual mode.
- (15) $t_{pll\ powerdown}$ is the PLL powerdown minimum pulse width.
- (16) t_{nll lock} is the time required for the transmitter CMU/ATX PLL to lock to the input reference clock frequency after coming out of reset.
- (17) To calculate the REFCLK rms phase jitter requirement for PCle at reference clock frequencies other than 100 MHz, use the following formula: REFCLK rms phase jitter at f(MHz) = REFCLK rms phase jitter at 100 MHz × 100/f.
- (18) The maximum peak to peak differential input voltage V_{ID} after device configuration is equal to 4 × (absolute V_{MAX} for receiver pin V_{ICM}).
- (19) For ES devices, R_{REF} is 2000 Ω ±1%.
- (20) To calculate the REFCLK phase noise requirement at frequencies other than 622 MHz, use the following formula: REFCLK phase noise at f(MHz) = REFCLK phase noise at 622 MHz + 20*log(f/622).
- (21) SFP/+ optical modules require the host interface to have RD+/- differentially terminated with 100 Ω. The internal OCT feature is available after the Stratix V FPGA configuration is completed. Altera recommends that FPGA configuration is completed before inserting the optical module. Otherwise, minimize unnecessary removal and insertion with unconfigured devices.
- (22) Refer to Figure 2.
- (23) For oversampling designs to support data rates less than the minimum specification, the CDR needs to be in LTR mode only.
- (24) I3YY devices can achieve data rates up to 10.3125 Gbps.
- (25) When you use fPLL as a TXPLL of the transceiver.
- (26) REFCLK performance requires to meet transmitter REFCLK phase noise specification.
- (27) Minimum eye opening of 85 mV is only for the unstressed input eye condition.

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Table 24 shows the maximum transmitter data rate for the clock network.

Table 24. Clock Network Maximum Data Rate Transmitter Specifications (1)

		ATX PLL			CMU PLL (2))		fPLL	
Clock Network	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span	Non- bonded Mode (Gbps)	Bonded Mode (Gbps)	Channel Span
x1 ⁽³⁾	14.1	_	6	12.5	_	6	3.125	_	3
x6 ⁽³⁾	_	14.1	6	_	12.5	6	_	3.125	6
x6 PLL Feedback ⁽⁴⁾	_	14.1	Side- wide	_	12.5	Side- wide	_	_	_
xN (PCIe)	_	8.0	8	_	5.0	8	_	_	_
xN (Native PHY IP)	8.0	8.0	Up to 13 channels above and below PLL	7.99	7.99	Up to 13 channels above	3.125	3.125	Up to 13 channels above
XIV (IVALIVE PRY IP)	_	8.01 to 9.8304	Up to 7 channels above and below PLL	7.99	7.99	and below PLL	J. 125	3.123	and below PLL

Notes to Table 24:

⁽¹⁾ Valid data rates below the maximum specified in this table depend on the reference clock frequency and the PLL counter settings. Check the MegaWizard message during the PHY IP instantiation.

⁽²⁾ ATX PLL is recommended at 8 Gbps and above data rates for improved jitter performance.

⁽³⁾ Channel span is within a transceiver bank.

⁽⁴⁾ Side-wide channel bonding is allowed up to the maximum supported by the PHY IP.

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Table 25 shows the approximate maximum data rate using the standard PCS.

Table 25. Stratix V Standard PCS Approximate Maximum Date Rate (1), (3)

Made (2)	Transceiver	PMA Width	20	20	16	16	10	10	8	8
Mode ⁽²⁾	Speed Grade	PCS/Core Width	40	20	32	16	20	10	16	8
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.5	5.8	5.2	4.72
	2	C3, I3, I3L core speed grade	9.8	9.0	7.84	7.2	5.3	4.7	4.24	3.76
FIFO		C1, C2, C2L, I2, I2L core speed grade	8.5	8.5	8.5	8.5	6.5	5.8	5.2	4.72
	3	I3YY core speed grade	10.3125	10.3125	7.84	7.2	5.3	4.7	4.24	3.76
	3	C3, I3, I3L core speed grade	8.5	8.5	7.84	7.2	5.3	4.7	4.24	3.76
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.8	4.2	3.84	3.44
	1	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C1, C2, C2L, I2, I2L core speed grade	12.2	11.4	9.76	9.12	6.1	5.7	4.88	4.56
	2	C3, I3, I3L core speed grade	9.8	9.0	7.92	7.2	4.9	4.5	3.96	3.6
Register		C1, C2, C2L, I2, I2L core speed grade	10.3125	10.3125	10.3125	10.3125	6.1	5.7	4.88	4.56
	3	I3YY core speed grade	10.3125	10.3125	7.92	7.2	4.9	4.5	3.96	3.6
	3	C3, I3, I3L core speed grade	8.5	8.5	7.92	7.2	4.9	4.5	3.96	3.6
		C4, I4 core speed grade	8.5	8.2	7.04	6.56	4.4	4.1	3.52	3.28

Notes to Table 25:

⁽¹⁾ The maximum data rate is in Gbps.

⁽²⁾ The Phase Compensation FIFO can be configured in FIFO mode or register mode. In the FIFO mode, the pointers are not fixed, and the latency can vary. In the register mode the pointers are fixed for low latency.

⁽³⁾ The maximum data rate is also constrained by the transceiver speed grade. Refer to Table 1 for the transceiver speed grade.

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Table 27 shows the $\ensuremath{V_{OD}}$ settings for the GX channel.

Table 27. Typical V $_{\text{OD}}$ Setting for GX Channel, TX Termination = 100 Ω $^{(2)}$

Symbol	V _{OD} Setting	V _{op} Value (mV)	V _{op} Setting	V _{op} Value (mV)
	0 (1)	0	32	640
	1 (1)	20	33	660
	2 (1)	40	34	680
	3 (1)	60	35	700
	4 (1)	80	36	720
	5 ⁽¹⁾	100	37	740
	6	120	38	760
	7	140	39	780
	8	160	40	800
	9	180	41	820
	10	200	42	840
	11	220	43	860
	12	240	44	880
	13	260	45	900
	14	280	46	920
V op differential peak to peak	15	300	47	940
typical ⁽³⁾	16	320	48	960
	17	340	49	980
	18	360	50	1000
	19	380	51	1020
	20	400	52	1040
	21	420	53	1060
	22	440	54	1080
	23	460	55	1100
	24	480	56	1120
	25	500	57	1140
	26	520	58	1160
	27	540	59	1180
	28	560	60	1200
	29	580	61	1220
	30	600	62	1240
	31	620	63	1260

Note to Table 27:

- (1) If TX termination resistance = 100Ω , this VOD setting is illegal.
- (2) The tolerance is +/-20% for all VOD settings except for settings 2 and below.
- (3) Refer to Figure 2.

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 1 of 5) $^{(1)}$

Symbol/	Conditions	5	Transceive Speed Grade			Transceive peed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	5
Reference Clock	l		<u>I</u>	U.			<u>I</u>	<u>I</u>
Supported I/O Standards	Dedicated reference clock pin	1.2-V PCN	1L, 1.4-V PC	ML, 1.5-V P(CML, 2.5-V I and HCSL	PCML, Diffe	rential LVPE	ECL, LVDS
otandardo	RX reference clock pin		1.4-V PCML	., 1.5-V PCN	IL, 2.5-V PC	ML, LVPEC	L, and LVDS	3
Input Reference Clock Frequency (CMU PLL) ⁽⁶⁾	_	40	_	710	40	_	710	MHz
Input Reference Clock Frequency (ATX PLL) (6)	_	100	_	710	100	_	710	MHz
Rise time	20% to 80%	_	_	400	_	_	400	
Fall time	80% to 20%	_	_	400	_	<u> </u>	400	ps
Duty cycle	_	45	_	55	45	_	55	%
Spread-spectrum modulating clock frequency	PCI Express (PCIe)	30	_	33	30	_	33	kHz
Spread-spectrum downspread	PCle		0 to -0.5	_	_	0 to -0.5	_	%
On-chip termination resistors (19)	_	_	100	_	_	100	_	Ω
Absolute V _{MAX} (3)	Dedicated reference clock pin	_	_	1.6	_	_	1.6	V
	RX reference clock pin	_	_	1.2	_	_	1.2	
Absolute V _{MIN}	_	-0.4	_	_	-0.4		_	V
Peak-to-peak differential input voltage	_	200	_	1600	200	_	1600	mV
V _{ICM} (AC coupled)	Dedicated reference clock pin		1050/1000	2)	1	050/1000	2)	mV
	RX reference clock pin	1	.0/0.9/0.85	(22)	1.	0/0.9/0.85	(22)	V
V _{ICM} (DC coupled)	HCSL I/O standard for PCIe reference clock	250	_	550	250	_	550	mV

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 3 of 5) $^{(1)}$

Symbol/	Conditions		Transceiver Speed Grade			Transceive peed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Differential on-chip termination resistors (7)	GT channels	_	100	_	_	100	_	Ω
	85-Ω setting	_	85 ± 30%	_	_	85 ± 30%	_	Ω
Differential on-chip termination resistors	100-Ω setting	_	100 ± 30%	_	_	100 ± 30%	_	Ω
for GX channels (19)	120-Ω setting	_	120 ± 30%	_	_	120 ± 30%	_	Ω
	150-Ω setting	_	150 ± 30%	_	_	150 ± 30%	_	Ω
V _{ICM} (AC coupled)	GT channels	_	650	_	_	650	_	mV
	VCCR_GXB = 0.85 V or 0.9 V	_	600	_	_	600	_	mV
VICM (AC and DC coupled) for GX Channels	VCCR_GXB = 1.0 V full bandwidth	_	700	_	_	700	_	mV
	VCCR_GXB = 1.0 V half bandwidth	_	750	_	_	750	_	mV
t _{LTR} ⁽⁹⁾	_	_	_	10	_	_	10	μs
t _{LTD} ⁽¹⁰⁾	_	4	_	_	4	_	_	μs
t _{LTD_manual} (11)		4	_	_	4	_	_	μs
t _{LTR_LTD_manual} (12)		15	_	_	15	_	_	μs
Run Length	GT channels	_	_	72	_	_	72	CID
nuii Leiigiii	GX channels				(8)			
CDR PPM	GT channels	_	_	1000	_	_	1000	± PPM
ODITITIVI	GX channels				(8)			
Programmable	GT channels	_	_	14	_	_	14	dB
equalization (AC Gain) ⁽⁵⁾	GX channels				(8)			
Programmable	GT channels	_	_	7.5	_		7.5	dB
DC gain ⁽⁶⁾	GX channels				(8)			
Differential on-chip termination resistors ⁽⁷⁾	GT channels		100	_	_	100	_	Ω
Transmitter	· '		•			•	•	
Supported I/O Standards	_			1.4-V	and 1.5-V F	PCML		
Data rate (Standard PCS)	GX channels	600	_	8500	600	_	8500	Mbps
Data rate (10G PCS)	GX channels	600	_	12,500	600		12,500	Mbps

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Table 28. Transceiver Specifications for Stratix V GT Devices (Part 4 of 5) $^{(1)}$

Symbol/	Conditions		Transceive peed Grade			Transceive Deed Grade		Unit
Description		Min	Тур	Max	Min	Тур	Max	
Data rate	GT channels	19,600	_	28,050	19,600	_	25,780	Mbps
Differential on-chip	GT channels	_	100	_		100	<u> </u>	Ω
termination resistors	GX channels			•	(8)		<u>'</u>	
\/	GT channels	_	500	_	_	500	_	mV
V _{OCM} (AC coupled)	GX channels			•	(8)		<u>'</u>	
Diag/Fall time	GT channels	_	15	_	_	15	_	ps
Rise/Fall time	GX channels		<u>I</u>		(8)			
Intra-differential pair skew	GX channels				(8)			
Intra-transceiver block transmitter channel-to- channel skew	GX channels				(8)			
Inter-transceiver block transmitter channel-to- channel skew	GX channels	(8)						
CMU PLL								
Supported Data Range	_	600	_	12500	600	_	8500	Mbps
t _{pll_powerdown} (13)	_	1	_	_	1	_	_	μs
t _{pll_lock} (14)	_	_	_	10	_	_	10	μs
ATX PLL								
	VCO post- divider L=2	8000	_	12500	8000	_	8500	Mbps
	L=4	4000	_	6600	4000	_	6600	Mbps
Supported Data Rate	L=8	2000	_	3300	2000	_	3300	Mbps
Range for GX Channels	L=8, Local/Central Clock Divider =2	1000	_	1762.5	1000	_	1762.5	Mbps
Supported Data Rate Range for GT Channels	VCO post- divider L=2	9800	_	14025	9800	_	12890	Mbps
t _{pll_powerdown} (13)	_	1	_	_	1	_	_	μs
t _{pll_lock} (14)	_	_	_	10	_	_	10	μs
fPLL			•					
Supported Data Range	_	600	_	3250/ 3.125 ⁽²³⁾	600	_	3250/ 3.125 ⁽²³⁾	Mbps
t _{pll_powerdown} (13)	_	1	_	_	1	_	_	μs

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Table 36. High-Speed I/O Specifications for Stratix V Devices (1), (2) (Part 3 of 4)

			C1		C2,	C2L, I	2, I2L	C3,	13, I3L	., I3YY		C4,I4	4	
Symbol	Conditions	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
t _{DUTY}	Transmitter output clock duty cycle for both True and Emulated Differential I/O Standards	45	50	55	45	50	55	45	50	55	45	50	55	%
	True Differential I/O Standards	_	_	160	_	_	160	_	_	200	_	_	200	ps
t _{RISE} & t _{FALL}	Emulated Differential I/O Standards with three external output resistor networks	_		250	_	_	250	_		250	_		300	ps
	True Differential I/O Standards	_	_	150	_		150		_	150		_	150	ps
TCCS	Emulated Differential I/O Standards	_	_	300	_	_	300	_		300	_		300	ps
Receiver														
	SERDES factor J = 3 to 10 (11), (12), (13), (14), (15), (16)	150	_	1434	150	_	1434	150	_	1250	150	_	1050	Mbps
True Differential I/O Standards	SERDES factor J ≥ 4 LVDS RX with DPA (12), (14), (15), (16)	150	_	1600	150	_	1600	150	_	1600	150	_	1250	Mbps
- f _{HSDRDPA} (data rate)	SERDES factor J = 2, uses DDR Registers	(6)	_	(7)	(6)	_	(7)	(6)		(7)	(6)		(7)	Mbps
	SERDES factor J = 1, uses SDR Register	(6)	_	(7)	(6)	_	(7)	(6)		(7)	(6)	_	(7)	Mbps

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Duty Cycle Distortion (DCD) Specifications

Table 44 lists the worst-case DCD for Stratix V devices.

Table 44. Worst-Case DCD on Stratix V I/O Pins (1)

Symbol	C	1	C2, C2	L, I2, I2L		3, I3L, 3YY	C4	1,14	Unit
-	Min	Max	Min	Max	Min	Max	Min	Max	
Output Duty Cycle	45	55	45	55	45	55	45	55	%

Note to Table 44:

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POR Delay Specification

Power-on reset (POR) delay is defined as the delay between the time when all the power supplies monitored by the POR circuitry reach the minimum recommended operating voltage to the time when the nSTATUS is released high and your device is ready to begin configuration.



For more information about the POR delay, refer to the *Hot Socketing and Power-On Reset in Stratix V Devices* chapter.

Table 45 lists the fast and standard POR delay specification.

Table 45. Fast and Standard POR Delay Specification (1)

POR Delay	Minimum	Maximum
Fast	4 ms	12 ms
Standard	100 ms	300 ms

Note to Table 45:

JTAG Configuration Specifications

Table 46 lists the JTAG timing parameters and values for Stratix V devices.

Table 46. JTAG Timing Parameters and Values for Stratix V Devices

Symbol	Description	Min	Max	Unit
t _{JCP}	TCK clock period (2)	30	_	ns
t _{JCP}	TCK clock period (2)	167	_	ns
t _{JCH}	TCK clock high time (2)	14	_	ns
t _{JCL}	TCK clock low time (2)	14	_	ns
t _{JPSU (TDI)}	TDI JTAG port setup time	2	_	ns
t _{JPSU (TMS)}	TMS JTAG port setup time	3	_	ns

⁽¹⁾ The DCD numbers do not cover the core clock network.

⁽¹⁾ You can select the POR delay based on the MSEL settings as described in the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

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Table 47. Uncompressed .rbf Sizes for Stratix V Devices

Family	Device	Package	Configuration .rbf Size (bits)	IOCSR .rbf Size (bits) (4), (5)
Stratix V E (1)	5SEE9	_	342,742,976	700,888
Stratix V L 17	5SEEB	_	342,742,976	700,888

Notes to Table 47:

- (1) Stratix V E devices do not have PCI Express® (PCIe®) hard IP. Stratix V E devices do not support the CvP configuration scheme.
- (2) 36-transceiver devices.
- (3) 24-transceiver devices.
- (4) File size for the periphery image.
- (5) The IOCSR .rbf size is specifically for the CvP feature.

Use the data in Table 47 to estimate the file size before design compilation. Different configuration file formats, such as a hexadecimal (.hex) or tabular text file (.ttf) format, have different file sizes. For the different types of configuration file and file sizes, refer to the Quartus II software. However, for a specific version of the Quartus II software, any design targeted for the same device has the same uncompressed configuration file size. If you are using compression, the file size can vary after each compilation because the compression ratio depends on your design.

For more information about setting device configuration options, refer to *Configuration, Design Security, and Remote System Upgrades in Stratix V Devices.* For creating configuration files, refer to the *Quartus II Help*.

Table 48 lists the minimum configuration time estimates for Stratix V devices.

Table 48. Minimum Configuration Time Estimation for Stratix V Devices

	Banker		Active Serial (1))	Fas	t Passive Parall	el ⁽²⁾
Variant	Member Code	Width	DCLK (MHz)	Min Config Time (s)	Width	DCLK (MHz)	Min Config Time (s)
	A3	4	100	0.534	32	100	0.067
	AS	4	100	0.344	32	100	0.043
	A4	4	100	0.534	32	100	0.067
	A5	4	100	0.675	32	100	0.084
	A7	4	100	0.675	32	100	0.084
GX	A9	4	100	0.857	32	100	0.107
	AB	4	100	0.857	32	100	0.107
	B5	4	100	0.676	32	100	0.085
	B6	4	100	0.676	32	100	0.085
	В9	4	100	0.857	32	100	0.107
	BB	4	100	0.857	32	100	0.107
GT	C5	4	100	0.675	32	100	0.084
G1	C7	4	100	0.675	32	100	0.084

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Table 49. DCLK-to-DATA[] Ratio (1) (Part 2 of 2)

Configuration Scheme	Decompression	Design Security	DCLK-to-DATA[] Ratio
	Disabled	Disabled	1
FPP ×32	Disabled	Enabled	4
	Enabled	Disabled	8
	Enabled	Enabled	8

Note to Table 49:

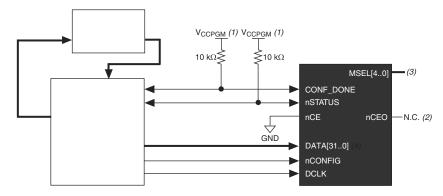
(1) Depending on the DCLK-to-DATA [] ratio, the host must send a DCLK frequency that is r times the data rate in bytes per second (Bps), or words per second (Wps). For example, in FPP ×16 when the DCLK-to-DATA [] ratio is 2, the DCLK frequency must be 2 times the data rate in Wps. Stratix V devices use the additional clock cycles to decrypt and decompress the configuration data.



If the DCLK-to-DATA[] ratio is greater than 1, at the end of configuration, you can only stop the DCLK (DCLK-to-DATA[] ratio -1) clock cycles after the last data is latched into the Stratix V device.

Figure 11 shows the configuration interface connections between the Stratix V device and a MAX II or MAX V device for single device configuration.

Figure 11. Single Device FPP Configuration Using an External Host



Notes to Figure 11:

- (1) Connect the resistor to a supply that provides an acceptable input signal for the Stratix V device. V_{CCPGM} must be high enough to meet the V_{IH} specification of the I/O on the device and the external host. Altera recommends powering up all configuration system I/Os with V_{CCPGM}.
- (2) You can leave the nceo pin unconnected or use it as a user I/O pin when it does not feed another device's nce pin.
- (3) The MSEL pin settings vary for different data width, configuration voltage standards, and POR delay. To connect MSEL, refer to the MSEL Pin Settings section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (4) If you use FPP $\times 8$, use DATA [7..0]. If you use FPP $\times 16$, use DATA [15..0].

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FPP Configuration Timing when DCLK-to-DATA [] = 1

Figure 12 shows the timing waveform for FPP configuration when using a MAX II or MAX V device as an external host. This waveform shows timing when the DCLK-to-DATA[] ratio is 1.

Figure 12. FPP Configuration Timing Waveform When the DCLK-to-DATA[] Ratio is 1 (1), (2)



Notes to Figure 12:

- (1) Use this timing waveform when the DCLK-to-DATA[] ratio is 1.
- (2) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic-high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (3) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (4) After power-up, before and during configuration, CONF DONE is low.
- (5) Do not leave DCLK floating after configuration. DCLK is ignored after configuration is complete. It can toggle high or low if required.
- (6) For FPP ×16, use DATA [15..0]. For FPP ×8, use DATA [7..0]. DATA [31..0] are available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings.
- (7) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high when the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (8) After the option bit to enable the <code>INIT_DONE</code> pin is configured into the device, the <code>INIT_DONE</code> goes low.

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Table 51 lists the timing parameters for Stratix V devices for FPP configuration when the DCLK-to-DATA [] ratio is more than 1.

Table 51. FPP Timing Parameters for Stratix V Devices When the DCLK-to-DATA[] Ratio is >1 $^{(1)}$

Symbol	Parameter	Minimum	Maximum	Units
t _{CF2CD}	nconfig low to conf_done low	_	600	ns
t _{CF2ST0}	nconfig low to nstatus low	_	600	ns
t _{CFG}	nCONFIG low pulse width	2	_	μS
t _{STATUS}	nstatus low pulse width	268	1,506 ⁽²⁾	μS
t _{CF2ST1}	nconfig high to nstatus high	_	1,506 ⁽²⁾	μS
t _{CF2CK} (5)	nconfig high to first rising edge on DCLK	1,506	_	μS
t _{ST2CK} (5)	nstatus high to first rising edge of DCLK	2	_	μS
t _{DSU}	DATA[] setup time before rising edge on DCLK	5.5	_	ns
t _{DH}	DATA[] hold time after rising edge on DCLK	N-1/f _{DCLK} ⁽⁵⁾	_	S
t _{CH}	DCLK high time	$0.45 \times 1/f_{MAX}$	_	S
t _{CL}	DCLK low time	$0.45 \times 1/f_{MAX}$	_	S
t _{CLK}	DCLK period	1/f _{MAX}	_	S
f	DCLK frequency (FPP ×8/×16)	_	125	MHz
f _{MAX}	DCLK frequency (FPP ×32)	_	100	MHz
t _R	Input rise time	_	40	ns
t _F	Input fall time	_	40	ns
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	t _{CD2CU} + (8576 × CLKUSR period) ⁽⁴⁾	_	_

Notes to Table 51:

- (1) Use these timing parameters when you use the decompression and design security features.
- (2) You can obtain this value if you do not delay configuration by extending the nconfig or nstatus low pulse width.
- (3) The minimum and maximum numbers apply only if you use the internal oscillator as the clock source for initializing the device.
- (4) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on these pins, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (5) N is the DCLK-to-DATA ratio and f_{DCLK} is the DCLK frequency the system is operating.
- (6) If nstatus is monitored, follow the t_{status} specification. If nstatus is not monitored, follow the t_{cfack} specification.

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Table 53. AS Timing Parameters for AS \times 1 and AS \times 4 Configurations in Stratix V Devices (1), (2) (Part 2 of 2)

Symbol	Parameter	Minimum	Maximum	Units
t _{CD2UM}	CONF_DONE high to user mode (3)	175	437	μS
t _{CD2CU}	CONF_DONE high to CLKUSR enabled	4 × maximum DCLK period	_	_
t _{CD2UMC}	CONF_DONE high to user mode with CLKUSR option on	$\begin{array}{c} t_{\text{CD2CU}} + (8576 \times \\ \text{CLKUSR period}) \end{array}$	_	_

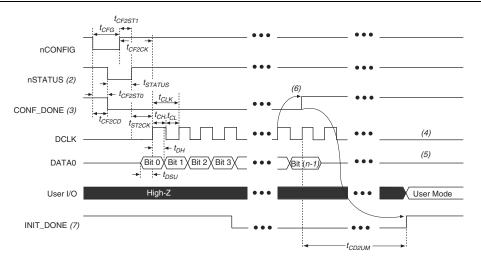
Notes to Table 53:

- (1) The minimum and maximum numbers apply only if you choose the internal oscillator as the clock source for initializing the device.
- $(2) \quad t_{\text{CF2CD}}, t_{\text{CF2ST0}}, t_{\text{CFG}}, t_{\text{STATUS}}, \text{ and } t_{\text{CF2ST1}} \text{ timing parameters are identical to the timing parameters for PS mode listed in Table 54 on page 63}.$
- (3) To enable the CLKUSR pin as the initialization clock source and to obtain the maximum frequency specification on this pin, refer to the Initialization section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

Passive Serial Configuration Timing

Figure 15 shows the timing waveform for a passive serial (PS) configuration when using a MAX II device, MAX V device, or microprocessor as an external host.

Figure 15. PS Configuration Timing Waveform (1)



Notes to Figure 15:

- (1) The beginning of this waveform shows the device in user mode. In user mode, nCONFIG, nSTATUS, and CONF_DONE are at logic high levels. When nCONFIG is pulled low, a reconfiguration cycle begins.
- (2) After power-up, the Stratix V device holds nSTATUS low for the time of the POR delay.
- (3) After power-up, before and during configuration, CONF DONE is low.
- (4) Do not leave DCLK floating after configuration. You can drive it high or low, whichever is more convenient.
- (5) DATAO is available as a user I/O pin after configuration. The state of this pin depends on the dual-purpose pin settings in the **Device and Pins Option**.
- (6) To ensure a successful configuration, send the entire configuration data to the Stratix V device. CONF_DONE is released high after the Stratix V device receives all the configuration data successfully. After CONF_DONE goes high, send two additional falling edges on DCLK to begin initialization and enter user mode.
- (7) After the option bit to enable the INIT DONE pin is configured into the device, the INIT DONE goes low.

Page 64 I/O Timing

Remote System Upgrades

Table 56 lists the timing parameter specifications for the remote system upgrade circuitry.

Table 56. Remote System Upgrade Circuitry Timing Specifications

Parameter	Minimum	Maximum	Unit
t _{RU_nCONFIG} (1)	250	_	ns
t _{RU_nRSTIMER} (2)	250	_	ns

Notes to Table 56:

- (1) This is equivalent to strobing the reconfiguration input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the Remote System Upgrade State Machine section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.
- (2) This is equivalent to strobing the reset_timer input of the ALTREMOTE_UPDATE megafunction high for the minimum timing specification. For more information, refer to the User Watchdog Timer section of the "Configuration, Design Security, and Remote System Upgrades in Stratix V Devices" chapter.

User Watchdog Internal Circuitry Timing Specification

Table 57 lists the operating range of the 12.5-MHz internal oscillator.

Table 57. 12.5-MHz Internal Oscillator Specifications

Minimum	Typical	Maximum	Units
5.3	7.9	12.5	MHz

I/O Timing

Altera offers two ways to determine I/O timing—the Excel-based I/O Timing and the Quartus II Timing Analyzer.

Excel-based I/O timing provides pin timing performance for each device density and speed grade. The data is typically used prior to designing the FPGA to get an estimate of the timing budget as part of the link timing analysis. The Quartus II Timing Analyzer provides a more accurate and precise I/O timing data based on the specifics of the design after you complete place-and-route.

You can download the Excel-based I/O Timing spreadsheet from the Stratix V Devices Documentation web page.

Programmable IOE Delay

Table 58 lists the Stratix V IOE programmable delay settings.

Table 58. IOE Programmable Delay for Stratix V Devices (Part 1 of 2)

Parameter	Available Settings	Min Offset	Fast Model		Slow Model							
			Industrial	Commercial	C1	C2	C3	C4	12	13, 13YY	14	Unit
D1	64	0	0.464	0.493	0.838	0.838	0.924	1.011	0.844	0.921	1.006	ns
D2	32	0	0.230	0.244	0.415	0.415	0.459	0.503	0.417	0.456	0.500	ns

Page 66 Glossary

Table 60. Glossary (Part 2 of 4)

Letter	Subject	Definitions
G		
Н	_	-
1		
J	JTAG Timing Specifications	High-speed I/O block—Deserialization factor (width of parallel data bus). JTAG Timing Specifications: TMS TDI TCK TJPSU TJ
K L M N	_	
P	PLL Specifications	Diagram of PLL Specifications (1) CLKOUT Pins Four Core Clock Reconfigurable in User Mode External Feedback Note: (1) Core Clock can only be fed by dedicated clock input pins or PLL outputs.
Q	_	-
R	R _L	Receiver differential input discrete resistor (external to the Stratix V device).
	_ <u>-</u>	1

Document Revision History Page 71

Table 61. Document Revision History (Part 3 of 3)

■ Updated Table 2, Table 6, Table 7, Table 20, Table 23, Table 27, Table 47, Table 2013 2.7 ■ Added Table 24, Table 48 ■ Updated Figure 9, Figure 10, Figure 11, Figure 12 ■ Updated Table 7, Table 9, Table 20, Table 23, Table 27, Table 30, Table 31, Table 46 ■ Updated "Maximum Allowed Overshoot and Undershoot Voltage" ■ Updated "Maximum Allowed Overshoot and Undershoot Voltage" ■ Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, TaTable 30, Table 32, Table 35 ■ Added Table 33 ■ Added "Fast Passive Parallel Configuration Timing" ■ Added "Added "Passive Serial Configuration Timing" ■ Added "Passive Serial Configuration Timing" ■ Added "Remote System Upgrades" ■ Added "Initialization" ■ Added "Initialization" ■ Added "Raw Binary File Size" ■ Added Figure 1, Figure 2, and Figure 3. ■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 40, Table 4 Table 56, and Table 59. ■ Various edits throughout to fix bugs.	
December 2012 2.5 December 2012 D	able 60
December 2012 2.6 Updated Table 7, Table 9, Table 20, Table 23, Table 27, Table 30, Table 31, Table 46 Updated "Maximum Allowed Overshoot and Undershoot Voltage" Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Tatable 30, Table 32, Table 35 Added Table 33 Added "Fast Passive Parallel Configuration Timing" Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Raw Binary File Size" Added "Raw Binary File Size" Added Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
Table 46 Updated "Maximum Allowed Overshoot and Undershoot Voltage" Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Ta Table 30, Table 32, Table 35 Added Table 33 Added "Fast Passive Parallel Configuration Timing" Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 40, Table 40, Table 40, Table 56, and Table 59.	
Updated "Maximum Allowed Overshoot and Undershoot Voltage" Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Ta Table 30, Table 32, Table 35 Added Table 33 Added "Fast Passive Parallel Configuration Timing" Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 40, Table 40, Table 40, Table 56, and Table 59.	Table 35,
December 2012 2.5 Updated Table 3, Table 6, Table 7, Table 8, Table 23, Table 24, Table 25, Table 30, Table 32, Table 35 Added Table 33 Added "Fast Passive Parallel Configuration Timing" Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 7, Table 30, Table 31, Table 32, Table 38, Table 39, Table 40, Table 4, Table 56, and Table 59.	
Table 30, Table 35 Added Table 33 Added "Fast Passive Parallel Configuration Timing" Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 7able 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
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December 2012 Added "Active Serial Configuration Timing" Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
December 2012 2.5 Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
 Added "Passive Serial Configuration Timing" Added "Remote System Upgrades" Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59. 	
 Added "User Watchdog Internal Circuitry Timing Specification" Added "Initialization" Added "Raw Binary File Size" Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59. 	
■ Added "Initialization" ■ Added "Raw Binary File Size" ■ Added Figure 1, Figure 2, and Figure 3. ■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
■ Added "Raw Binary File Size" ■ Added Figure 1, Figure 2, and Figure 3. ■ Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
June 2012 Added Figure 1, Figure 2, and Figure 3. Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 36, Table 36, Table 37, Table 38, Table 39, Table 40, Table 40, Table 56, and Table 59.	
June 2012 Updated Table 1, Table 2, Table 3, Table 6, Table 11, Table 22, Table 23, Table 30, Table 31, Table 32, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
Table 30, Table 31, Table 35, Table 38, Table 39, Table 40, Table 4 Table 56, and Table 59.	
■ Changed title of document to <i>Stratix V Device Datasheet</i> .	
■ Removed document from the Stratix V handbook and made it a separate document	cument.
February 2012 2.3 Updated Table 1–22, Table 1–29, Table 1–31, and Table 1–31.	
December 2011 2.2 ■ Added Table 2–31.	
■ Updated Table 2–28 and Table 2–34.	
■ Added Table 2–2 and Table 2–21 and updated Table 2–5 with information at Stratix V GT devices.	out
November 2011 2.1 Updated Table 2–11, Table 2–13, Table 2–20, and Table 2–25.	
■ Various edits throughout to fix SPRs.	
■ Updated Table 2–4, Table 2–18, Table 2–19, Table 2–21, Table 2–22, Table 2 Table 2–24.	2–23, and
May 2011 2.0 ■ Updated the "DQ Logic Block and Memory Output Clock Jitter Specifications	s" title.
■ Chapter moved to Volume 1.	
■ Minor text edits.	
■ Updated Table 1–2, Table 1–4, Table 1–19, and Table 1–23.	
December 2010 1.1 Converted chapter to the new template.	
■ Minor text edits.	
July 2010 1.0 Initial release.	